

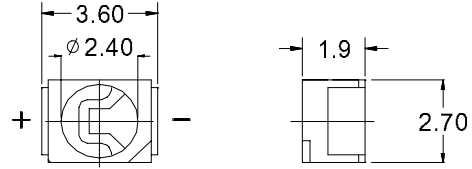


BVS-301QS4

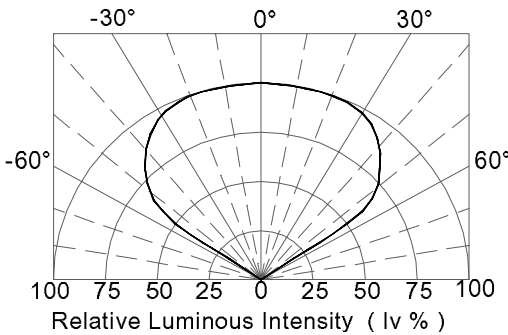
PACKAGE CONFIGURATION

DESCRIPTION

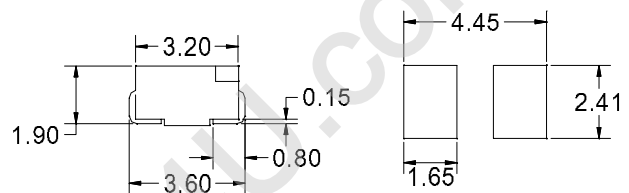
Dice Material : AlGaInP/GaAs Amber
Light Color : Amber Color
Lens Color : Water Transparent



RADIATION PATTERN



**INFRARED/VAPOR PHASE
REFLOW SOLDERING**



Tolerance ± 0.25 mm

ABSOLUTE MAXIMUM RATINGS AT Ta = 25 °C

PARAMETER	MAX.	UNIT
Power Dissipation	95	mW
Continuous Forward Current	35	mA
Peak Forward Current (1/10 Duty Cycle , 0.1ms Pulse Width)	80	mA
Reverse Voltage	5	V
Derating Linear From 50 °C	0.35	mA/°C
Operating Temperature Range	-40 to + 100	°C
Storage Temperature Range	-40 to + 100	°C
Reflow Soldering Condition 230 °C for 10 seconds		

ELECTRICAL / OPTICAL CHARACTERISTICS AT Ta = 25 °C

SYMBOL	PARAMETER	TEST COND.	MIN.	TYP.	MAX.	UNIT
V _F	Forward Voltage	I _F = 20 mA		2	2.6	V
I _R	Reverse Current	V _R = 5V			100	μA
λ _p	Peak Emission Wavelength	I _F = 20 mA		611		nm
λ _d	Dominant Wavelength	I _F = 20 mA		605		nm
2θ _{1/2}	Viewing Angle	I _F = 20 mA		110		Deg

BIN GRADE LIMITS (I F = 20 mA) LUMINOUS INTENSITY / mcd

Bin	B	C	D	E	F	G
Min.	130	168	218	280	360	465
Max.	168	218	280	360	465	600

Tolerance $\pm 15\%$ mcd

*Bright View reserves the rights to alter specifications and remove availability of products at any time without notice.

*Dominant Wavelength, λ_d is according to CIE Chromaticity Diagram base on color of lamps.

*θ_{1/2} is the off-axis angle where the luminous intensity is one half the on-axis intensity.



Apply to BVS-3XX · 1XX series.

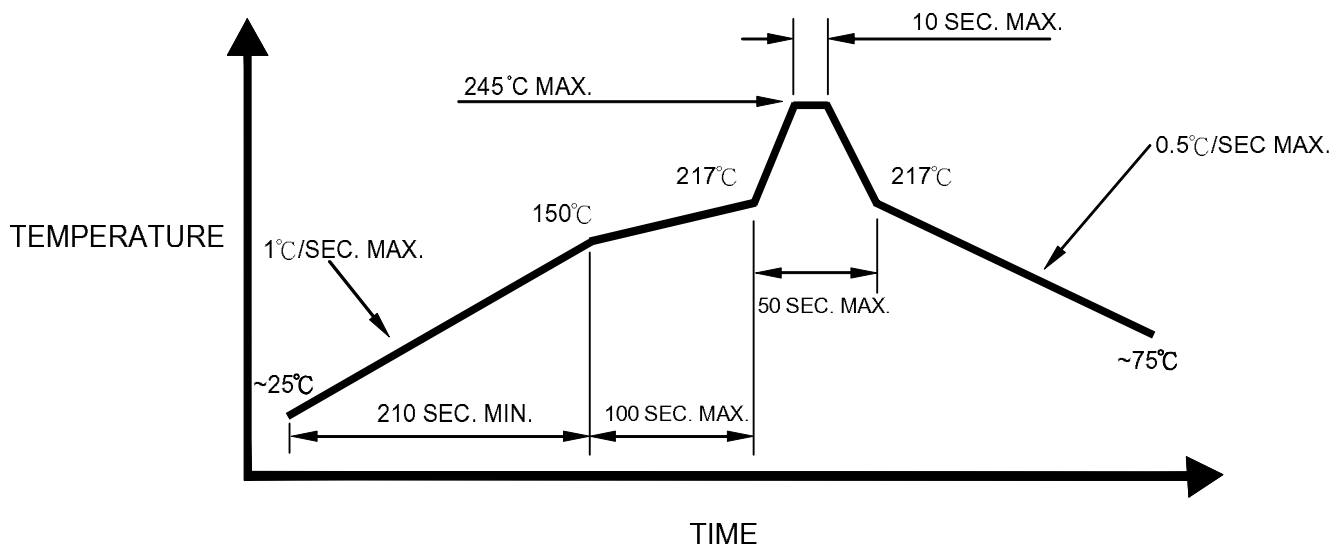
Description:

(1) Manual soldering (We do not recommend this method strongly.)

- (1.1) To prevent cracking, please bake (65°C, 24hrs) before soldering.
- (1.2) Temperature at tip of iron: 250°C Max. (25W)
- (1.3) It's banned to load any stress on the resin during soldering.
- (1.4) Soldering time: 3 sec. Max. (one time only)

(2) Reflow Soldering

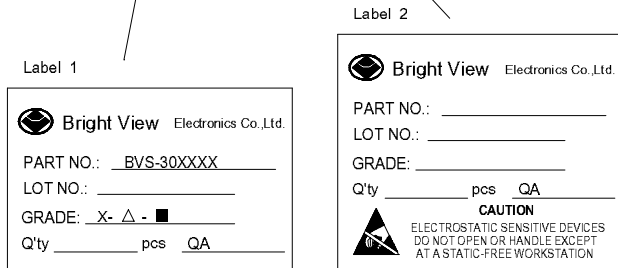
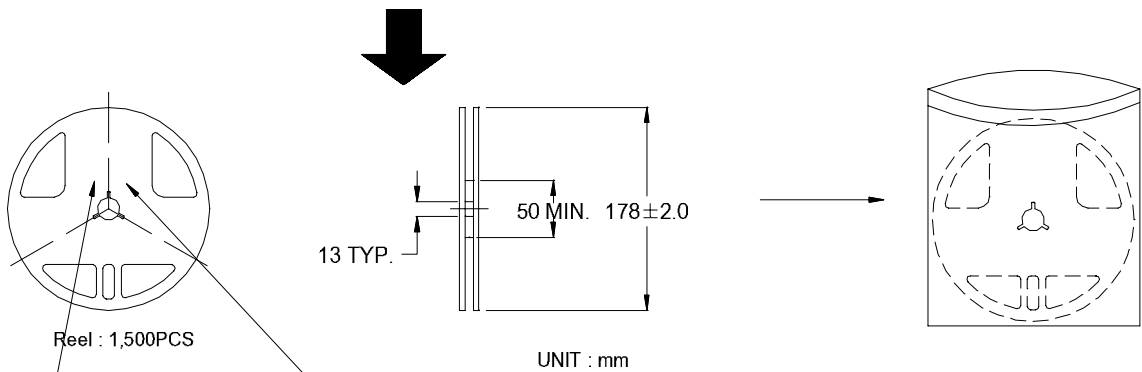
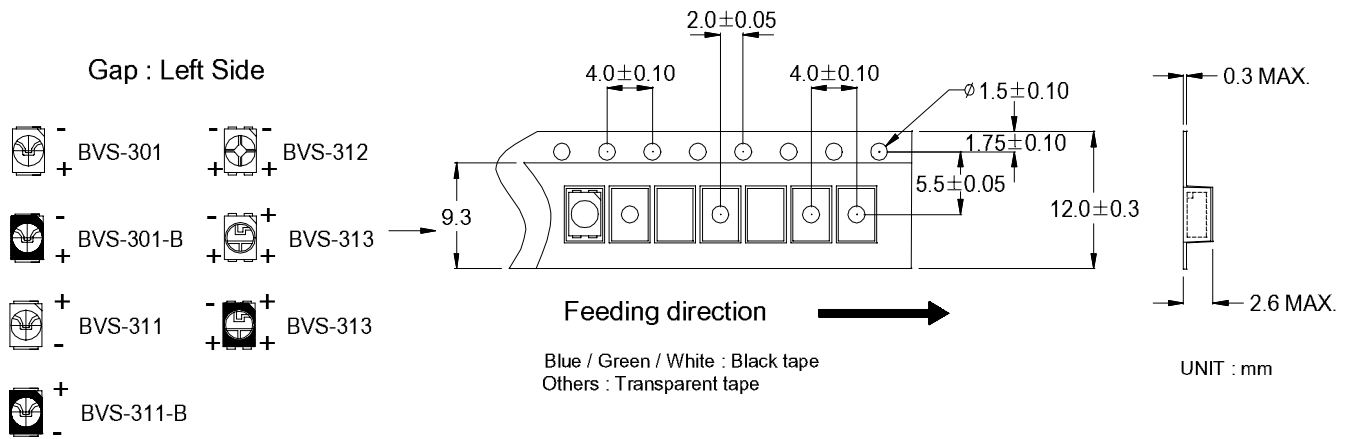
- (2.1) To prevent cracking, please bake (65°C, 24hrs) before soldering.
- (2.2) When soldering, do not put stress on the LEDs during heating.
- (2.3) Never take next process until the component is cooled down to room temperature after reflow.
- (2.4) After soldering, do not warp the circuit board.
- (2.5) The recommended reflow soldering profile (measuring on the surface of the LED resin) is following:



The reflow temperature 240°C~245°C is recommended and the soldering temperature should be not higher than 245°C (one time only)



TOP LEDS PACKING (A)



Normal

X: Bin grade
△: Wavelength
■: Vf

